Type-C USB Port Protection Switch

Features

- Fully USB Data Port Protection
- V_{DD} 0 V 5.5 V (12 V DC tolerant)
- -18 V to +20 V DC Tolerance on HSD± Port
- ±25 V IEC 61000-4-5 Surge Protection w/o External TVS
- V_{DD} Operating Range, 2.7 V-5.5 V
- HSD RON: 5 Ω Typical
- C_{ON} = 5 pF Typical
- Wide -3 dB Bandwidth: > 720 MHz
- Low Power Operation: $I_{CC} < 10 \mu A$ (Typical)
- Over Voltage Protection: 3.6 V & 4.5 V

Typical Applications

- Smartphones
- Tablets
- Laptops

Safety Mechanisms Highlight

- 3.6 V & 4.5 V OVP Trip Point
- ±25 V Surge Protection without Need for External TVS

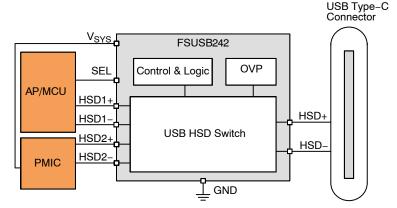


Figure 1. Application Schematic



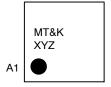
ON Semiconductor®

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WLCSP9 1.20 × 1.20 CASE 567UL

MARKING DIAGRAM

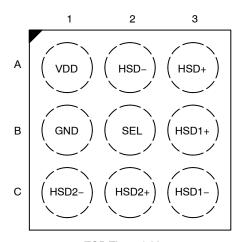


MT = Specific Device Code&K = 2 Digit Lot Run Code

X = Year

Y = 2 Week Data CodeZ = Plant Code

PIN CONNECTION



TOP Through View

ORDERING INFORMATION

See detailed ordering and shipping information on page 11 of this data sheet.

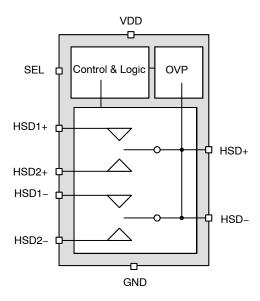


Figure 2. Simplified Block Diagram

Table 1. PIN FUNCTION DESCRIPTION

CSP Bump	Name	Туре	Description	
A1	VDD	Power	Supply Power	
B1	GND	Ground	Ground	
A3	HSD+	Data	Common High Speed Data Bus	
A2	HSD-	Data	Common High Speed Data Bus	
B3	HSD1+	Data	Multiplexed High Speed Data Port 1	
СЗ	HSD1-	Data	Multiplexed High Speed Data Port 1	
C2	HSD2+	Data	Multiplexed High Speed Data Port 2	
C1	HSD2-	Data	Multiplexed High Speed Data Port 2	
B2	SEL	I/O	Tri-Input HSD Switch Select & /OE	

Table 2. SWITCH TRUTH TABLE CONFIGURATION

VDD	SEL	Switch Configuration
UVLO	X	Switch off High impedance
Valid	0	HSD+ = HSD1+, HSD- = HSD1-
Valid	1	HSD+ = HSD2+, HSD- = HSD2-
Valid	Float/High–Z	Switch Disable High impedance

APPLICATION INFORMATION

Over Voltage Protection

Over voltage protection turns the switch off if the inputs HSD+/HSD- rise above the over voltage trip threshold.

Under Voltage Lockout

The under-voltage lockout on V_{DD} pin turns the switch off if the V_{DD} voltage drops below the lockout threshold. With the SELpin active, the input voltage rising above the UVLO threshold releases the lockout and enables the switch.

Tri-State Input Control Pin (SEL)

The SEL pin can be tri-stated to disable the switch to save power, there are a few ways to achieve this. If the SEL pin is controlled by GPIO in the system, if the GPIO pin has a High-Z state where the impedance of the High-Z state is

larger then 2.5 M Ω the switch will recognize the High–Z state and disable the switch. If the system does not have GPIO that supports High–Z state, the user can utilize 2 MOSFETs or a Logic Device to achieve the same result.

For GPIO

The SEL pin function below:

- If the input is pulled up with less than 50 k Ω it will be considered as Logic High
- If the input is pulled down with less than 50 kΩ it will be consider as Logic Low
- If the input is pulled up or down with more 2.5 M Ω it will be consider as float/High-Z

System Timing Diagram

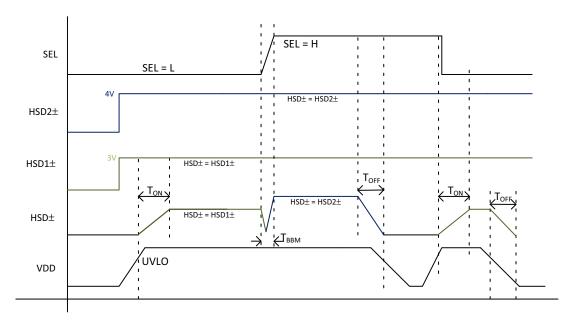


Figure 3. System Timing Plot

System Block Diagrams

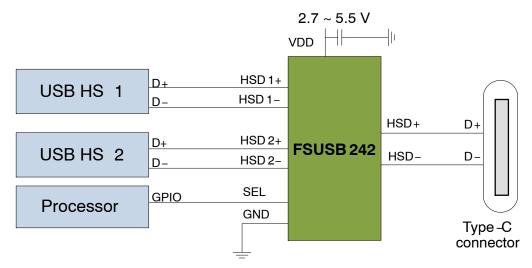


Figure 4. Application of 2x USB HS interface

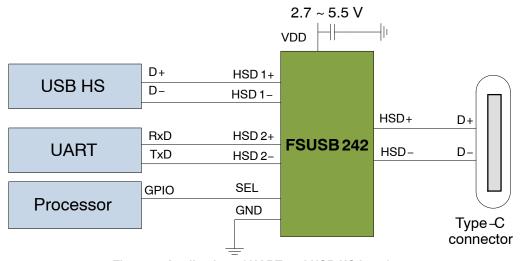


Figure 5. Application of UART and USB HS interface

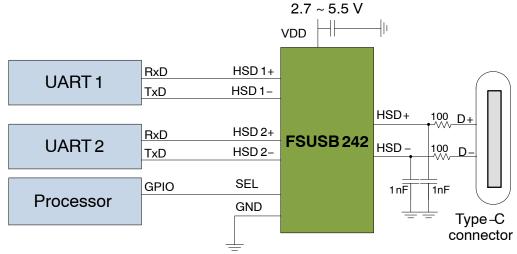


Figure 6. Application of 2x UART interface

When 2x UART signals are switched over FSUSB242, both 100 ohm series resistor and 1 nF bypass capacitors are recommended in the common switch path as above. If FSUSB242 is used to switch USB and UART signals, connect UART signals to HSD1.

USB High Speed Eye Diagram

$V_{DD} = 5.5 \ V \ HSD \ to \ HSD1 \ Path$

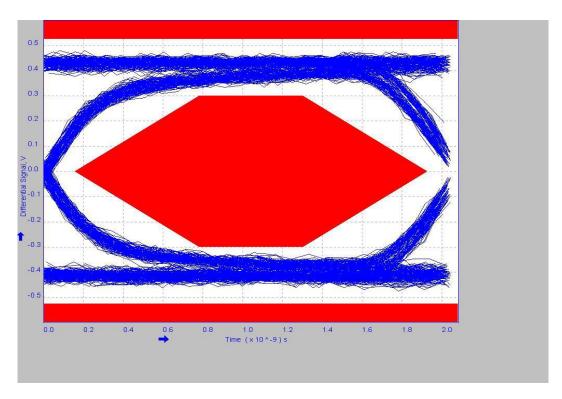


Figure 7. HS USB Eye @ V_{DD} = 5 V

 $V_{DD} = 2.7 \ V \ HSD \ to \ HSD2 \ Path$

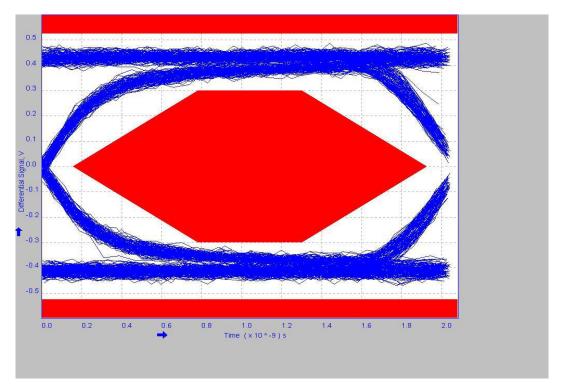


Figure 8. HS USB Eye @ V_{DD} = 2.7 V

Table 3. ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter			Min	Max	Unit
V_{DD}	Supply Voltage from V _{DD}			-0.5	12.0	V
V_{SW}	DC Input voltage tolerance for HSD±, to	DC Input voltage tolerance for HSD±, to GND			20	V
	DC Input voltage tolerance for HSD1±, HSD2± to GND			-1.2	6	V
V _{CONTROL}	DC Input Voltage (SEL)			-0.5	6	V
I _{SW}	DC HSD Switch Current				100	mA
I _{IK}	DC Input Diode Current			-50		mA
T _{STORAGE}	Storage Temperature Range			-65	+150	°C
TJ	Maximum Junction Temperature				+150	°C
TL	Lead Temperature (Soldering, 10 secon	nds)			+260	°C
ESD	IEC 61000-4-2 System ESD (Note 1)	Connector Pins (HSD±)	Air Gap	15		kV
			Contact	8		1
	Human Body Model, JEDEC	Power to GND	•	2		kV
	JESD22-A114	Internal Pin to GND (HSD1±, HSD2±)		2		
		External Pin to GND (HSD±)		14		
Charged Device Model, JEDEC All Pins LESD22-C101		All Pins		1		
	IEC 61000-4-5 Surge Protection	HSD±, to GND		±25		٧
		V _{DD} to GND		+12		V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 4. RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Тур	Max	Unit
V_{DD}	Supply Voltage	2.7	4.2	5.5	V
V _{SW1}	HSD1 Switch I/O Signal Swing Voltage (Note 2)	-0.5		3.6	V
V _{SW2}	HSD2 Switch I/O Signal Swing Voltage (Note 2)	-0.5		4.5	V
I _{CCSW}	Maximum HSD Switch Continuous Current			75	mA
V _{CNTRL}	Control Input Voltage (SEL)	-0.5		V_{DD}	V
T _A	Operating Temperature	-40		+85	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

Table 5. DC ELECTRICAL CHARACTERISTICS

(Unless otherwise specified: Recommended T_A and T_J temperature ranges. All typical values are at $T_A = 25^{\circ}$ C and $V_{DD} = 4.2 \text{ V}$ unless otherwise specified.)

				T _A = -40 to +85°C T _J = -40 to +125°C			
Symbol	Characteristic	V _{DD} (V)	Conditions	Min	Тур	Max	Unit
BASIC OPERA	BASIC OPERATION DEVICE						
I _{CC}	Quiescent Supply Current	2.7 to 5.5	WLCSP: /OE = H & L, I _{OUT} = 0		10		μΑ
I _{OFF}	Power-Off Leakage Current	0	V _{SWHSD1} = 0 V to 3.6 V, V _{SWHSD2} = 0 V to 4.5 V	-3		3	μΑ

^{1.} System level test that depends on end system for actual performance. These tests results are with external TVS protection. These specs are listed as general guidelines for expected performance in actual system and do not guarantee listed performance.

^{2.} The switch swing voltage is based on the OVP trip level, and when OVP triggers the switch will be disabled to protect the host and no longer in the standard operating condition, once over voltage is removed the device will automatically recover back to normal condition.

Table 5. DC ELECTRICAL CHARACTERISTICS (continued)

(Unless otherwise specified: Recommended T_A and T_J temperature ranges. All typical values are at $T_A = 25^{\circ}C$ and $V_{DD} = 4.2 \text{ V}$ unless otherwise specified.)

			T _A = -40 to +85°C T _J = -40 to +125°C				
Symbol	Characteristic	V _{DD} (V)	Conditions	Min	Тур	Max	Unit
BASIC OPERA	TION DEVICE						
I _{IN}	Control Input Leakage	2.7 to 5.5	V _{CNTRL} = 0 V to V _{DD}	-2		4	μА
l _{OZ}	Off State Leakage	2.7 to 5.5	HSD± ≥ 0 V, HSD1±, HSD2± ≤ 3.6 V	-3		5	μΑ
BASIC OPERA	TION HSD SWITCH					•	
R _{ON}	HSD Path On Resistance	2.7 to 5.5	I _{OUT} = 8 mA, V _{SW} = 0 V to 0.4 V		5		Ω
$\Delta R_{ extsf{ON}}$	HSD Path Delta R _{ON}	2.7 to 5.5	I _{OUT} = 8 mA, V _{SW} = 0 V to 0.4 V		0.15		Ω
V _{IH}	SEL Input Voltage High	2.7 to 5.5		1.3			V
V_{IM}	SEL Input Voltage Middle (Note 3)	2.7 to 5.5		0.8		1.0	٧
V _{IL}	SEL Input Voltage Low	2.7 to 5.5				0.5	V
Zfloat	Impedance to VDD or GND detected as a Float including VDD = 0	2.7 to 5.5		2.5			МΩ
Vov_trip1	Input OVP Lockout for HSD1 (FSUSB242UCX)	2.7 to 5.5	V _{HSD±} Rising, SEL = 0	3.6	3.8	4.0	V
			V _{HSD±} Falling, SEL = 0	3.3	3.5		
	Input OVP Lockout for HSD1 (FSUSB242UCXF45)	2.7 to 5.5	V _{HSD±} Rising, SEL = 0	4.5	4.7	4.9	V
			V _{HSD±} Falling, SEL = 0	4.2	4.4		
V _{OV_TRIP2}	Input OVP Lockout for HSD2	2.7 to 5.5	V _{HSD±} Rising, SEL = 1	4.5	4.7	4.9	V
			V _{HSD±} Falling, SEL = 1	4.2	4.4		7
V _{OV TRIP3 F45}	Input OVP Lockout for both HSD1 and HSD2	2.7 to 5.5	V _{HSD±} Rising	4.5	4.7	4.9	V
(14010 4)	TIOD I did TIOD2		V _{HSD±} Falling	4.2	4.4		
V _{OV_HYS}	Input OVP Hysteresis	2.7 to 5.5			0.3		V
V _{NV_TRIP}	Input Negative Voltage	2.7 to 5.5	V _{HSD±} Falling		-1.0		V
	Lockout		V _{HSD±} Rising		-0.7		
V _{NV_HYS}	Input OVP Hysteresis	2.7 to 5.5			0.3		V
V _{CL}	Clamping Voltage	2.7 to 5.5	$V_{HSD\pm} \ge V_{OV_TRIP}$		4.5		V
V _{UVLO}	Under-Voltage Lockout		V _{DD} Rising		2.4	2.7	V
			V _{DD} Falling		2.3		1
TSD	Thermal Shutdown (Note 3)		Shutdown Threshold		150		°C
			Return from Shutdown		130		
			Hysteresis		20		1

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Guaranteed by characterization or Design, not production tested.

4. FSUSB242F45UCX OVP threshold.

Table 6. AC ELECTRICAL CHARACTERISTICS

(Unless otherwise specified: Recommended T_A and T_J temperature ranges. All typical values are at T_A = 25°C and V_{DD} = 4.2 V unless otherwise specified.)

				T _A = -40 to +85°C T _J = -40 to +125°C			
Symbol	Characteristic	V _{DD} (V)	Conditions	Min	Тур	Max	Unit
HSD SWIT	CH TIMING PARAMETER	•		•	•		•
t _{OVP}	OVP Response Time (Note 53)	2.7 to 5.5	I_{OUT} = 8 mA, C_L = 5 pF, R_L = 50 Ω , $V_{HSD\pm}$ = 3.3 V to 4.9 V		0.35		μs
t _{ON}	Turn-On Time, SEL to Output	2.7 to 5.5	$R_L = 50 \Omega$, $C_L = 5 pF$		0.1		ms
t _{OFF}	Turn-Off Time, SEL to Output	2.7 to 5.5	$\begin{aligned} R_L &= 50 \ \Omega, \ C_L = 5 \ \text{pF}, \\ V_{SW} &= 0.8 \ \text{V} \end{aligned}$		0.2		μs
t _{PD}	Propagation Delay (Note 5)	2.7 to 5.5	$\begin{aligned} R_L &= 50 \ \Omega, \ C_L = 5 \ \text{pF}, \\ V_{SW} &= 0.8 \ \text{V} \end{aligned}$		1.3		ns
t _{BBM}	Break-Before-Make (Note 5)	2.7 to 5.5	$R_L = 50 \Omega$, $C_L = 5 pF$, $V_{SW1} = V_{SW2} = 0.8 V$		50		μs
t _{SK(P)}	Skew of Opposite Transitions of the Same Output (Note 5)	2.7 to 5.5	V_{SW} = 0.2 Vdiff _{PP} , R_L = 50 Ω , C_L = 5 pF		35		ps
tı	Total Jitter (Note 5)	2.7 to 5.5	$\begin{array}{c} V_{SW} = 0.2 \ V diff_{PP}, \ R_L = 50 \ \Omega, \\ C_L = 5 \ pF, \ t_R = t_F = 500 \ ps \\ (10-90\%) \ @ \ 480 \ Mbps \\ (PRBS = 2^{15} - 1) \end{array}$		250		ps
HSD± SWI	TCH CAPACITANCE	l.			l		
C _{IN}	Control Pin Input Capacitance (Note 5)	0			1.5		pF
C _{ON}	HSD± On Capacitance (Note 5)	2.7 to 5.5	SEL = L/H, f = 240 MHz		4		
C _{OFF}	HSD± Off Capacitance (Note 5)	2.7 to 5.5	SEL = Float, f = 240 MHz		3		
HSD SWIT	CH BANDWIDTH	•		•	•	•	•
BW	-3dB SDD21 Bandwidth	2.7 to 5.5	$R_L = 50 \Omega$, $C_L = 0 pF$		1000		MHz
	(Note 5)		R _L = 50 Ω, C _L = 5 pF		550		MHz
HSD SWIT	CH AC PARAMETER			•	•	•	•
O _{IRR}	Off Isolation (Note 5)	2.7 to 5.5	R _L = 50 Ω, f = 240 MHz		-35		dB
Xtalk	Non-Adjacent Channel Crosstalk (Note 5)	2.7 to 5.5	R_L = 50 Ω , f = 240 MHz		-40		dB

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

5. Guaranteed by characterization or Design, not production tested.

TEST DIAGRAMS

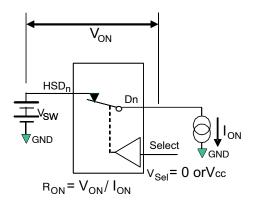
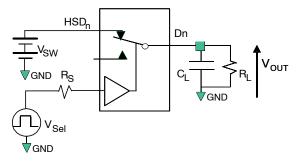


Figure 9. On Resistance



 R_L , R_S , and C_L are functions of the application environment (see AC Tables for specific values) C_L includes test fixture and stray capacitance.

Figure 11. AC Test Circuit Load

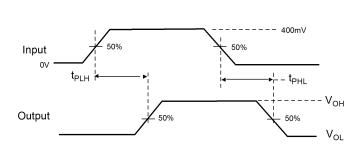
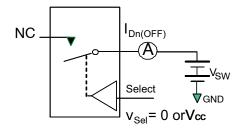


Figure 13. Propagation Delay (t_Rt_F - 500 ps)



**Each switch port is tested separately

Figure 10. Off Leakage

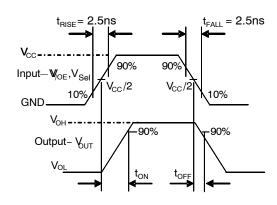


Figure 12. Turn-On / Turn-Off Waveforms

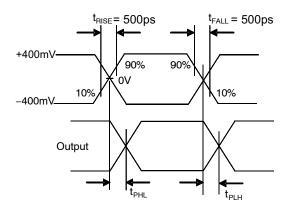


Figure 14. Intra-Pair Skew Test t_{SK(P)}

TEST DIAGRAMS (Continued)

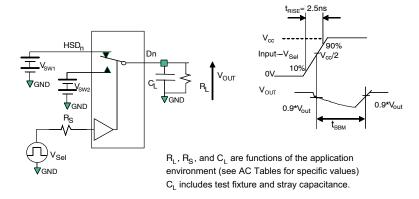


Figure 15. Break-Before-Make Interval Timing

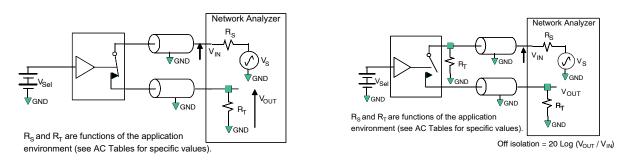


Figure 16. Bandwidth

Figure 17. Channel Off Isolation

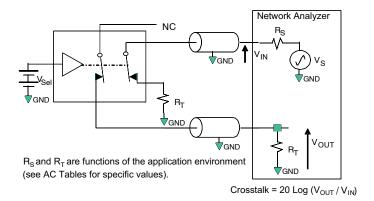
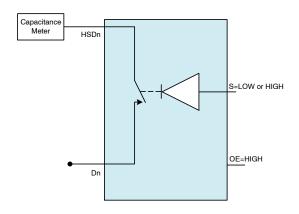


Figure 18. Non-Adjacent Channel-to-Channel Crosstalk

TEST DIAGRAMS (Continued)



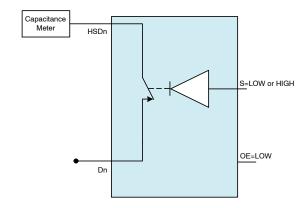


Figure 19. Channel Off Capacitance

Figure 20. Channel On Capacitance

ORDERING INFORMATION

Table 7. AVAILABLE PART NUMBERS

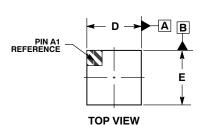
Part Number	Device Code	Operating Temperature Range	Package	Packing Method†
FSUSB242UCX	MT	−40 to 85°C	9-Ball WLCSP (1.20 x 1.20 mm)	Tape and Reel
FSUSB242F45UCX	MU	−40 to 85°C	9-Ball WLCSP (1.20 x 1.20 mm)	Tape and Reel

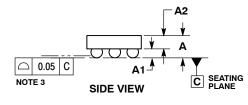
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

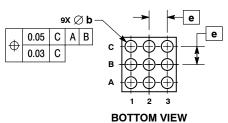


WLCSP9, 1.2x1.2x0.48 CASE 567UL **ISSUE A**

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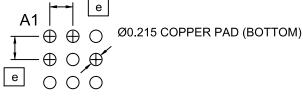


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- CONTROLLING DIMENSION: MILLIMETERS.
 COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

	MILLIMETERS							
DIM	MIN	MIN NOM MAX						
Α	0.450	0.488	0.526					
A1	0.176	0.196	0.216					
A2	0.274	0.292	0.310					
b	0.24	0.26	0.28					
D	1.14	1.20	1.26					
E	1.14	1.20	1.26					
_		0.40 BSC	:					

RECOMMENDED SOLDERING FOOTPRINT* (NSMD PAD TYPE)



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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